

VERSION SHOWING MARKED CHANGES TO THE APPLICATION

IN THE CLAIMS

1 1. (CANCEL)

1 2. (CANCEL)

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1 6. (CANCEL)

1 7. A process for underfilling an integrated circuit that is mounted to a substrate,  
2 comprising:

3 dispensing a first underfill material which becomes attached to the integrated circuit and  
4 the substrate; and,

5 dispensing a second underfill material which become attached to the integrated circuit  
6 and the substrate.

1 8. (Amended) The process as recited in claim 11 [7], wherein the first underfill  
2 material flows between the integrated circuit and the substrate.

1 9. (Amended) The [A] process as recited in claim 8, wherein the substrate moves  
2 within an oven while the first underfill material flows between the integrated circuit and the  
3 substrate.

1 10. (Amended) The process as recited in claim 11 [7], wherein the second underfill  
2 material is dispensed in a pattern which surrounds the first underfill material.

1 11. (Amended) A [The] process [as recited in claim 7, further comprising the step of]  
2 for underfilling an integrated circuit that is mounted to a substrate comprising:

3 heating the substrate before a [the] first underfill material is dispensed;

4 dispensing the first underfill material which becomes attached to the integrated circuit  
5 and the substrate; and,

6 dispensing a second underfill material which become attached to the integrated circuit  
7 and the substrate.

1 12. (Amended) The process as recited in claim 11, further comprising [the step of]  
2 heating the first underfill material to a partial gel state.

1 13. (Amended) The process as recited in claim 12, wherein the substrate is heated to a  
2 temperature that is greater than a temperature for heating [of] said [partially gelled] first underfill  
3 material to said partially gel state.

1 14. (Amended) The process as recited in claim 11 [7], further comprising [the step of]  
2 mounting the integrated circuit to the substrate with a solder bump before the first underfill  
3 material is dispensed.

1 15. (Amended) A process for mounting and underfilling an integrated circuit to a  
2 substrate, comprising:  
3 baking the substrate;  
4 mounting an integrated circuit to the substrate;  
5 dispensing a first underfill material onto the substrate, [wherein] the first underfill  
6 material flows between the integrated circuit and the substrate while the substrate moves through  
7 an oven; and,  
8 dispensing a second underfill material around the first underfill material.

1 16. (Amended) The process as recited in claim 15, further comprising [the step of]  
2 mounting the integrated circuit to the substrate with a solder bump before the first underfill  
3 material is dispensed.

1 17. (New) The process as recited in claim 15, wherein the baking of said substrate occurs  
2 before said first underfill material is dispensed.

1 18. (New) The process as recited in claim 15, wherein prior to dispensing the second  
2 underfill material, the method further comprises heating the first underfill material to a partial gel  
3 state.

1        19. (New) The process as recited in claim 18, wherein the substrate is baked at a  
2 temperature that is greater than a temperature for heating said first underfill material to said  
3 partially gel state.

1        20. (New) The process as recited in claim 19, wherein said temperature for heating  
2 said first underfill material to said partially gel state is greater than a temperature at which said  
3 second underfill material is dispensed.

1        21. (New) The process as recited in claim 13, wherein said temperature for heating  
2 said first underfill material to said partially gel state is greater than a temperature at which said  
3 second underfill material is dispensed.

1        22. (New) A process for mounting and underfilling an integrated circuit to a substrate,  
2 comprising:  
3        heating the substrate to a first temperature;  
4        mounting an integrated circuit to the substrate;  
5        dispensing a first underfill material onto the substrate and heating the first underfill  
6 material to a second temperature in which the first underfill material is in a partial gel state and  
7 flows between the integrated circuit and the substrate while the substrate moves through an oven;  
8 and,  
9        dispensing a second underfill material around the first underfill material.

1        23. (New) The process as recited in claim 22, further comprising mounting the  
2        integrated circuit to the substrate with a solder bump before the first underfill material is  
3        dispensed.

1        24. (New) The process as recited in claim 22, wherein the first temperature is greater  
2        than the second temperature.

1        25. (New) The process as recited in claim 24, wherein the second temperature is  
2        greater than a temperature at which the second underfill material is dispensed.

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CONCLUSION

In view of the foregoing, Applicants respectfully request examination of the pending claims. Examination of these claims at Examiner's earliest convenience is respectfully solicited.

Respectfully submitted,

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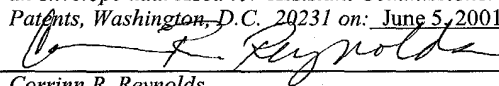
Dated: June 5, 2001

  
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06/5/01